TOSHIBA Field-Effect Transistor Silicon P-Channel MOS Type (U-MOSVI)

SSM6J212FE

○ Power Management Switch Applications

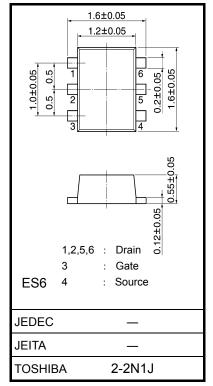
- 1.5-V drive
- Low ON-resistance: $R_{DS(ON)}$ = 94.0 m Ω (max) (@V_{GS} = -1.5 V)
 - $R_{DS(ON)} = 65.4 \text{ m}\Omega \text{ (max)} (@V_{GS} = -1.8 \text{ V})$ $R_{DS(ON)} = 49.0 \text{ m}\Omega \text{ (max)} (@V_{GS} = -2.5 \text{ V})$

 $R_{DS(ON)}$ = 40.7 m Ω (max) (@V_{GS} = -4.5 V)

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol		Rating	Unit	
Drain-source voltage		V _{DSS}		-20	V	
Gate-source voltage		V _{GSS}		± 8	V	
Drain current	DC	I _D (Note 1)		-4.0	A	
	Pulse	I _{DP} (Note 1)		-8.0		
Drain power dissipation		P _D (Note 2		500	mW	
			t = 10s	700	11100	
Channel temperature		T _{ch}		150	°C	
Storage temperature range		T _{stg}		-55 to 150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.



Weight : 3mg (typ.)

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

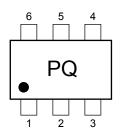
Note 1: The channel temperature should not exceed 150°C during use.

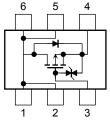
Note 2: Mounted on a FR4 board.

(25.4 mm \times 25.4 mm \times 1.6 mm, Cu Pad: 645 mm²)

Marking (Top View)

Equivalent Circuit





Unit: mm

Electrical Characteristics (Ta = 25°C)

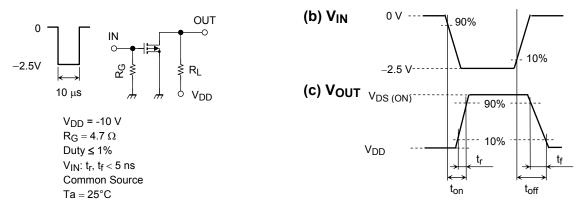
Chara	cteristic	Symbol	Test Conditions		Min	Тур.	Max	Unit
Drain-source breakdown voltage	V (BR) DSS	$I_D = -1 \text{ mA}, V_{GS} = 0 \text{ V}$		-20		_	V	
Drain-source breakdown vollage		V (BR) DSX	$I_{D} = -1 \text{ mA}, V_{GS} = 5 \text{ V}$	(Note 4)	-15			V
Drain cut-off current		I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V		_		-1	μA
Gate leakage current		I _{GSS}	$V_{GS}=\pm 8~V,~V_{DS}=0~V$		_	—	±1	μA
Gate threshold voltage		V _{th}	$V_{DS} = -3 V$, $I_D = -1 mA$		-0.3	—	-1.0	V
Forward transfer a	admittance	Y _{fs}	$V_{DS} = -3 V, I_D = -1.0 A$	(Note 3)	4.7	9.4		S
Drain-source ON-resistance		I_D = -3.0 A, V_{GS} = -4.5 V	(Note 3)	—	35.3	40.7	mΩ	
	Pro (ou)	$I_D = -2.0 \text{ A}, V_{GS} = -2.5 \text{ V}$	(Note 3)	—	41.3	49.0		
	R _{DS} (ON)	$I_D = -1.0 \text{ A}, V_{GS} = -1.8 \text{ V}$	(Note 3)	_	48.6	65.4		
		$I_D = -0.5 \text{ A}, V_{GS} = -1.5 \text{ V}$	(Note 3)	_	56.7	94.0		
Input capacitance		C _{iss}			_	970		
Output capacitance		Coss	V _{DS} = -10 V, V _{GS} = 0 V f = 1 MHz		_	127		pF
Reverse transfer capacitance		C _{rss}			_	109		
Switching time	Turn-on time	t _{on}	$V_{DD} = -10 \text{ V}, \text{ I}_{D} = -2.0 \text{ A}$		_	47		20
	Turn-off time	t _{off}	V_{GS} = 0 to -2.5 V, R_G = 4.7 Ω		_	143		ns
Total gate charge		Qg	- 4.0 A, חסע = -4.0 A,		_	14.1		
Gate-source charge		Q _{gs1}	$V_{DD} = -10 V$, $I_{DD} = -4.0 A$, $V_{GS} = -4.5 V$			1.7		nC
Gate-drain charge		Q _{gd}	VGS+.0 V			2.4	_	
Drain-source forward voltage		V _{DSF}	$I_D = 4.0 \text{ A}, V_{GS} = 0 \text{ V}$	(Note 3)	—	0.87	1.2	V

Note3: Pulse test

Note4: V_{DSX} mode (the application of a plus voltage between gate and source) may cause decrease in maximun rating of drain-source voltage

Switching Time Test Circuit

(a) Test Circuit



Notice on Usage

 V_{th} can be expressed as the voltage between gate and source when the low operating current value is I_D = -1 mA for this product. For normal switching operation, $V_{GS\ (on)}$ requires a higher voltage than V_{th} and $V_{GS\ (off)}$ requires a lower voltage than $V_{th.}$ (The relationship can be established as follows: $V_{GS\ (off)} < V_{th} < V_{GS\ (on).}$)

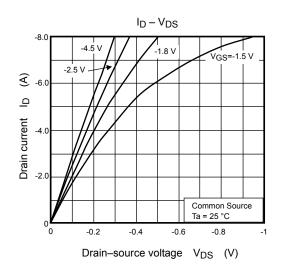
Take this into consideration when using the device.

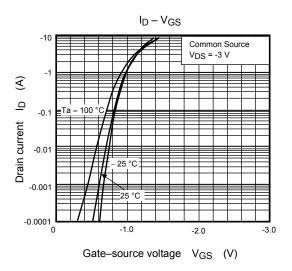
Handling Precaution

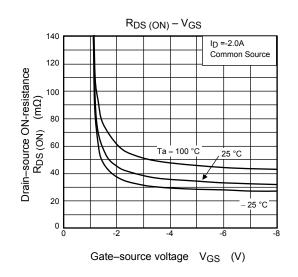
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

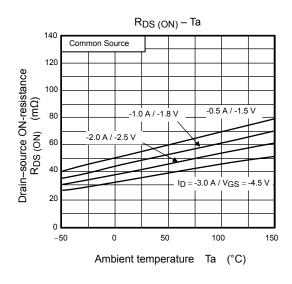
Thermal resistance $R_{th (ch-a)}$ and drain power dissipation P_D vary depending on board material, board area, board thickness and pad area. When using this device, please take heat dissipation into consideration

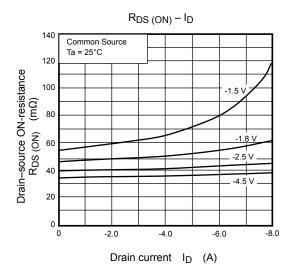
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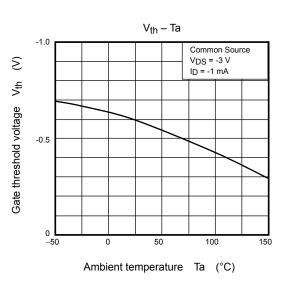




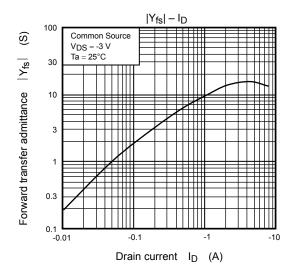


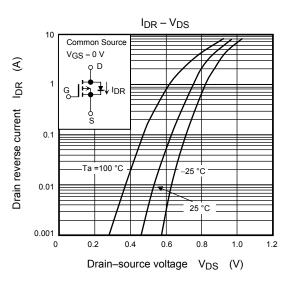


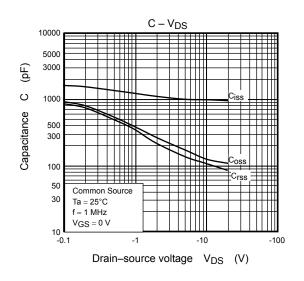


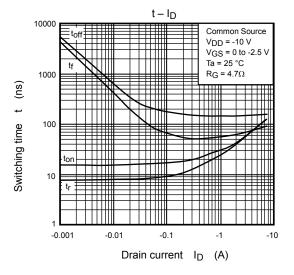


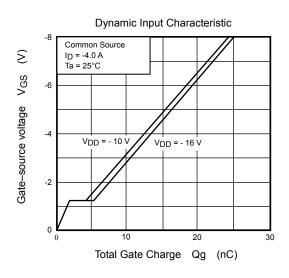
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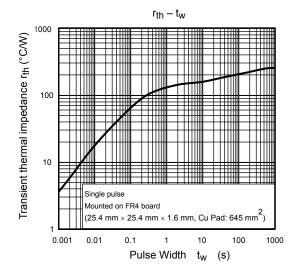


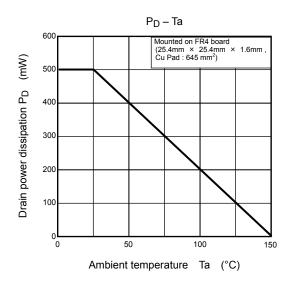






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